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IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

WWW - For www.nxp.com use www.ween-semi.com

Email - For salesaddresses@nxp.com use salesaddresses@ween-semi.com

For the copyright notice at the bottom of each page (or elsewhere in the document, depending on the version) “© **NXP Semiconductors N.V. {year}. All rights reserved**” becomes “© **WeEn Semiconductors Co., Ltd. {year}. All rights reserved**”

If you have any questions related to this document, please contact our nearest sales office via e-mail or phone (details via salesaddresses@ween-semi.com).

Thank you for your cooperation and understanding,

WeEn Semiconductors



DATA SHEET

BYV42E, BYV42EB series
Rectifier diodes
ultrafast, rugged

Product specification

July 1998



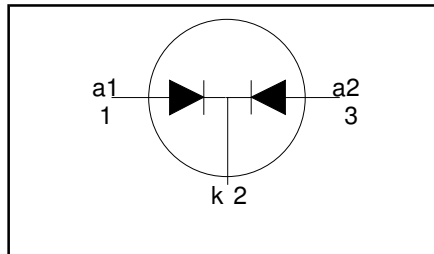
Rectifier diodes ultrafast, rugged

BYV42E, BYV42EB series

FEATURES

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- Reverse surge capability
- High thermal cycling performance
- Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$V_R = 150\text{ V} / 200\text{ V}$
$V_F \leq 0.85\text{ V}$
$I_{O(AV)} = 30\text{ A}$
$I_{RRM} = 0.2\text{ A}$
$t_r \leq 28\text{ ns}$

GENERAL DESCRIPTION

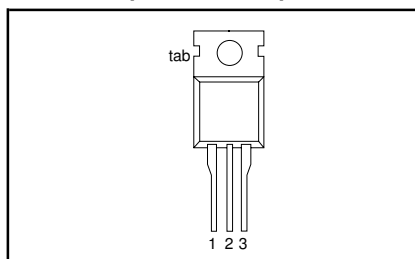
Dual, ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV42E series is supplied in the SOT78 conventional leaded package.
The BYV42EB series is supplied in the SOT404 surface mounting package.

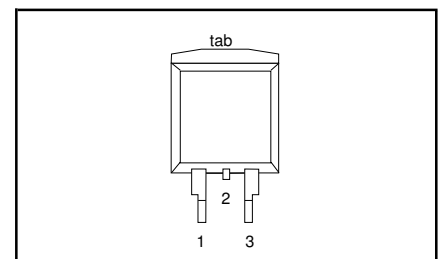
PINNING

PIN	DESCRIPTION
1	anode 1 (a)
2	cathode (k) ¹
3	anode 2 (a)
tab	cathode (k)

SOT78 (TO220AB)



SOT404



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
				BYV42E / BYV42EB		
V_{RRM}	Peak repetitive reverse voltage	$T_{mb} \leq 144\text{ }^\circ\text{C}$	-	-150	-200	V
V_{RWM}	Crest working reverse voltage		-	150	200	V
V_R	Continuous reverse voltage		-	150	200	V
$I_{O(AV)}$	Average rectified output current (both diodes conducting)	square wave $\delta = 0.5; T_{mb} \leq 108\text{ }^\circ\text{C}$	-	30		A
I_{FRM}	Repetitive peak forward current per diode	$t = 25\text{ }\mu\text{s}; \delta = 0.5;$ $T_{mb} \leq 108\text{ }^\circ\text{C}$	-	30		A
I_{FSM}	Non-repetitive peak forward current per diode	$t = 10\text{ ms}$	-	150		A
		$t = 8.3\text{ ms}$ sinusoidal; with reapplied	-	160		A
I_{RRM}	Repetitive peak reverse current per diode	$V_{RWM(max)}$ $t_p = 2\text{ }\mu\text{s}; \delta = 0.001$	-	0.2		A
I_{RSM}	Non-repetitive peak reverse current per diode	$t_p = 100\text{ }\mu\text{s}$	-	0.2		A
T_{stg}	Storage temperature		-40	150		$^\circ\text{C}$
T_j	Operating junction temperature		-	150		$^\circ\text{C}$

1. It is not possible to make connection to pin 2 of the SOT404 package
2. SOT78 package, For output currents in excess of 20 A, the cathode connection should be made to the mounting tab.

Rectifier diodes ultrafast, rugged

BYV42E, BYV42EB series

ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_C	Electrostatic discharge capacitor voltage	Human body model; $C = 250 \text{ pF}$; $R = 1.5 \text{ k}\Omega$	-	8	kV

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base	per diode	-	-	2.4	K/W
		both diodes	-	-	1.4	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	SOT78 package, in free air	-	60	-	K/W
		SOT404 and SOT428 packages, pcb mounted, minimum footprint, FR4 board	-	50	-	K/W

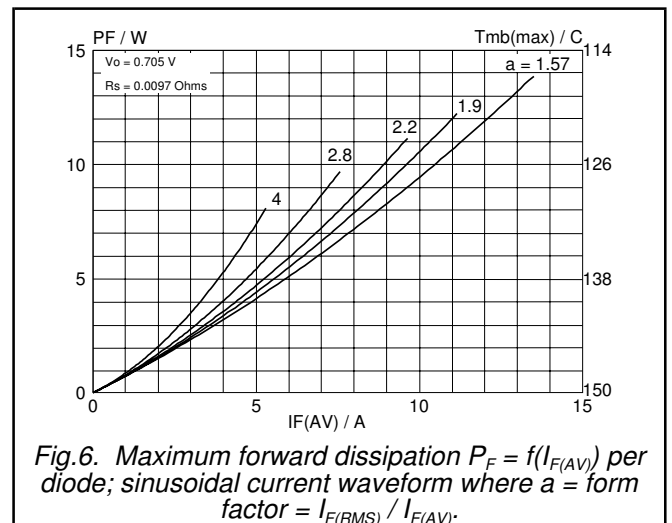
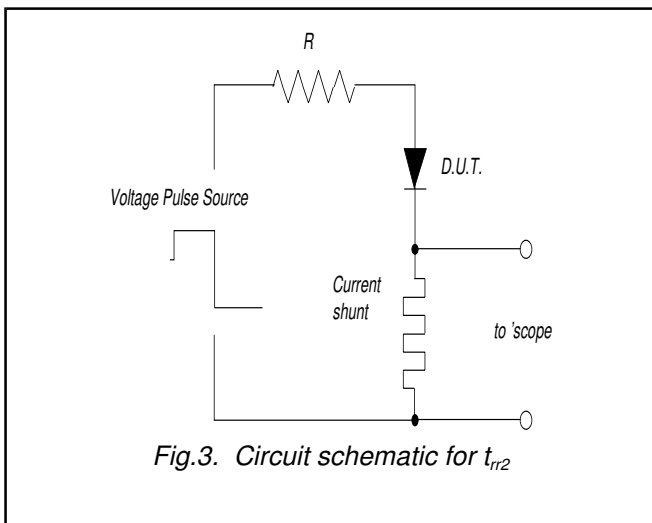
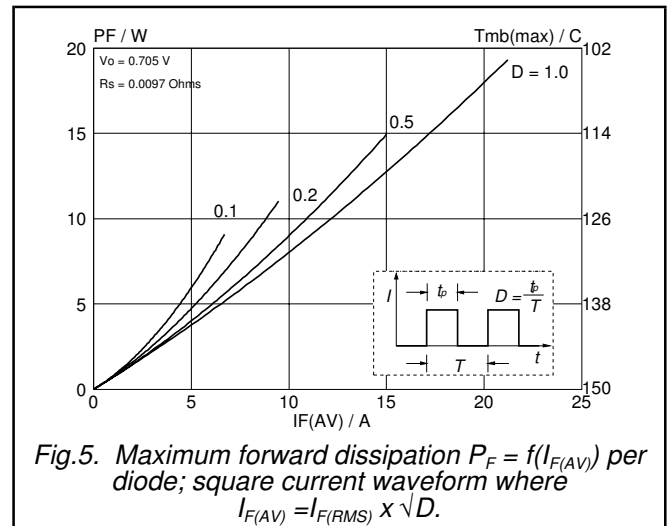
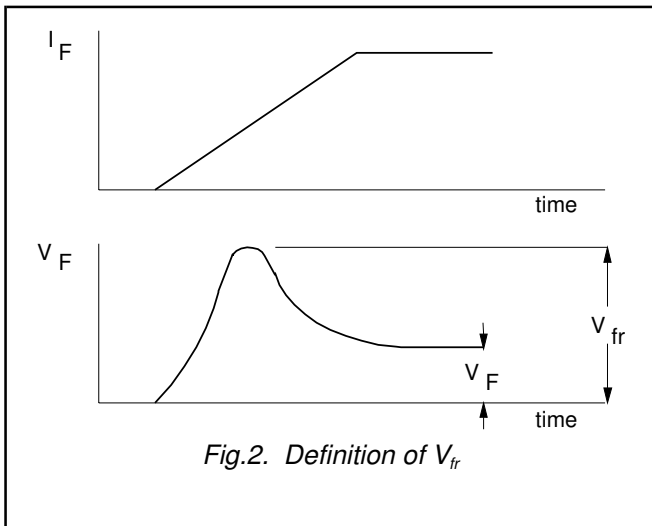
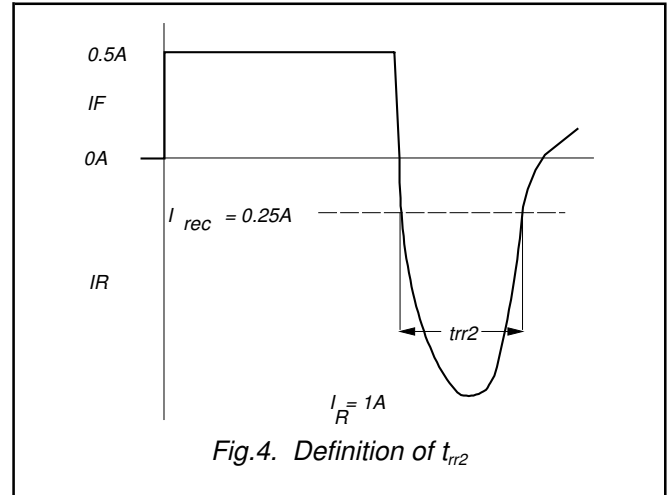
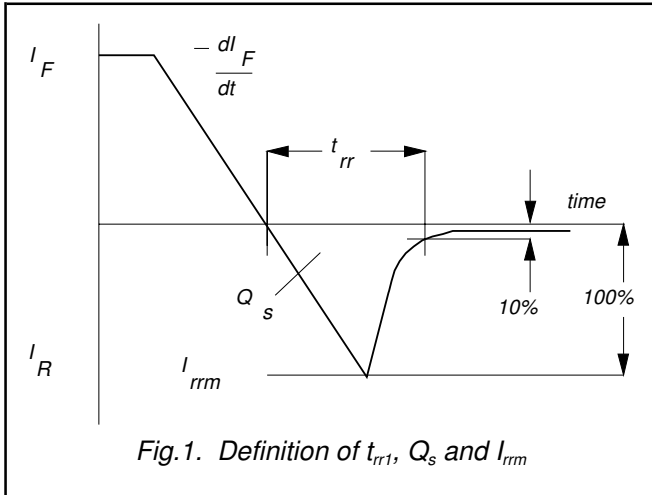
ELECTRICAL CHARACTERISTICS

characteristics are per diode at $T_j = 25 \text{ }^\circ\text{C}$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	$I_F = 15 \text{ A}$; $T_j = 150 \text{ }^\circ\text{C}$	-	0.78	0.85	V
		$I_F = 15 \text{ A}$	-	0.95	1.05	V
		$I_F = 30 \text{ A}$	-	1.00	1.20	V
I_R	Reverse current	$V_R = V_{RWM}$; $T_j = 100 \text{ }^\circ\text{C}$	-	0.5	1	mA
		$V_R = V_{RWM}$	-	10	100	μA
Q_s	Reverse recovery charge	$I_F = 2 \text{ A}$; $V_R \geq 30 \text{ V}$; $-di_F/dt = 20 \text{ A}/\mu\text{s}$	-	6	15	nC
t_{rr1}	Reverse recovery time	$I_F = 1 \text{ A}$; $V_R \geq 30 \text{ V}$; $-di_F/dt = 100 \text{ A}/\mu\text{s}$	-	20	28	ns
t_{rr2}	Reverse recovery time	$I_F = 0.5 \text{ A}$ to $I_R = 1 \text{ A}$; $I_{rec} = 0.25 \text{ A}$	-	13	22	ns
V_{fr}	Forward recovery voltage	$I_F = 1 \text{ A}$; $di_F/dt = 10 \text{ A}/\mu\text{s}$	-	1	-	V

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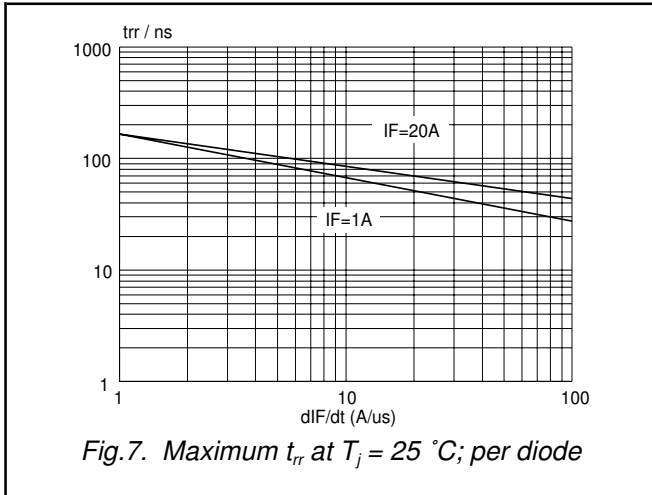


Fig.7. Maximum t_{rr} at $T_j = 25^\circ C$; per diode

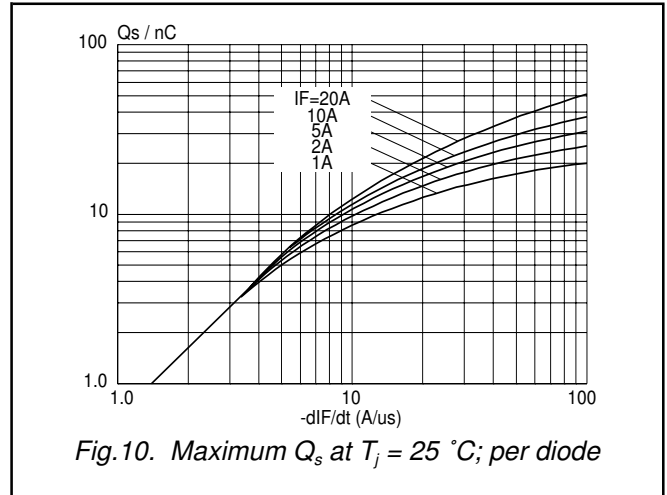


Fig.10. Maximum Q_s at $T_j = 25^\circ C$; per diode

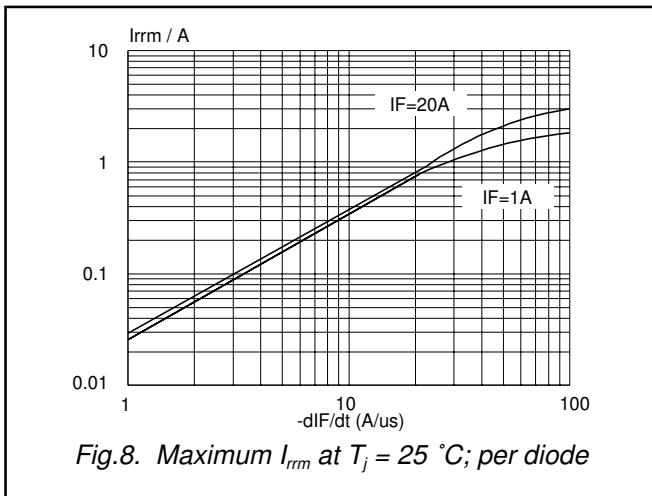


Fig.8. Maximum I_{rrm} at $T_j = 25^\circ C$; per diode

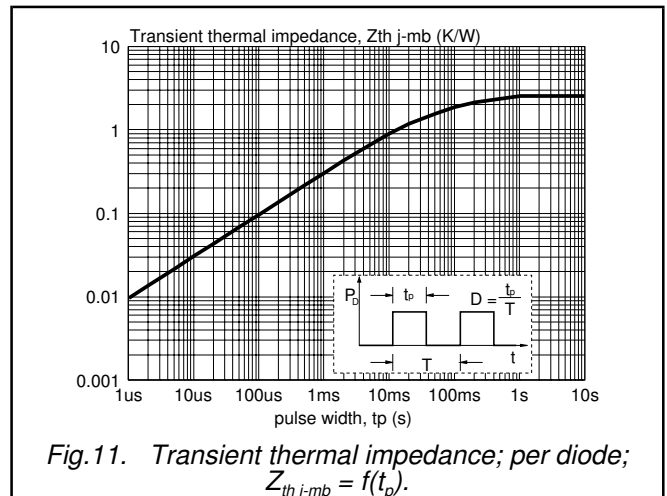


Fig.11. Transient thermal impedance; per diode;
 $Z_{th\ j-mb} = f(t_p)$.

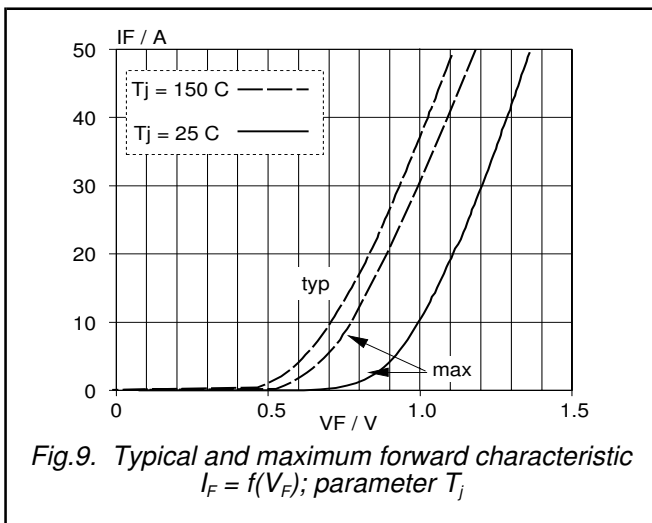
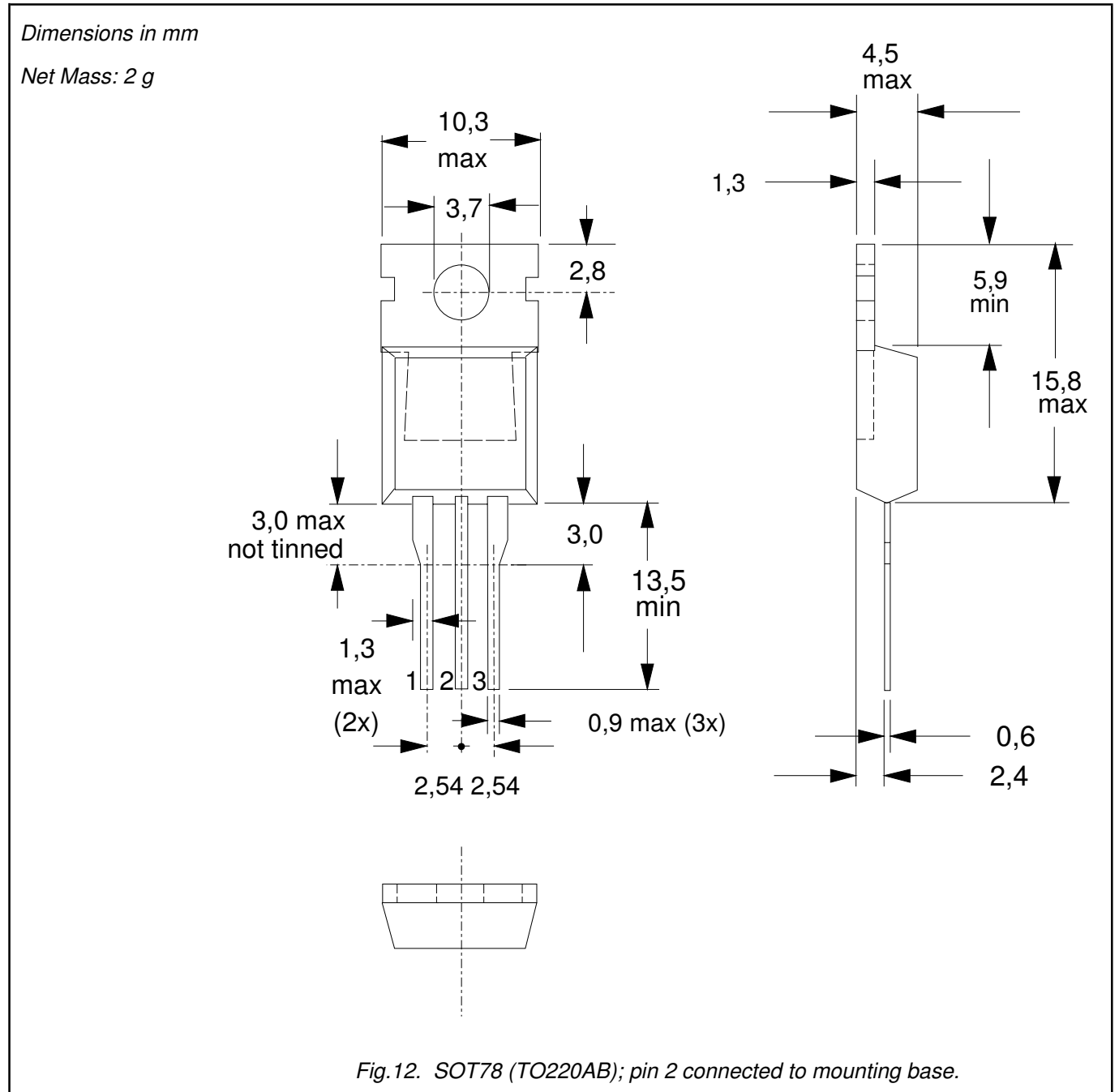


Fig.9. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_j

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MECHANICAL DATA



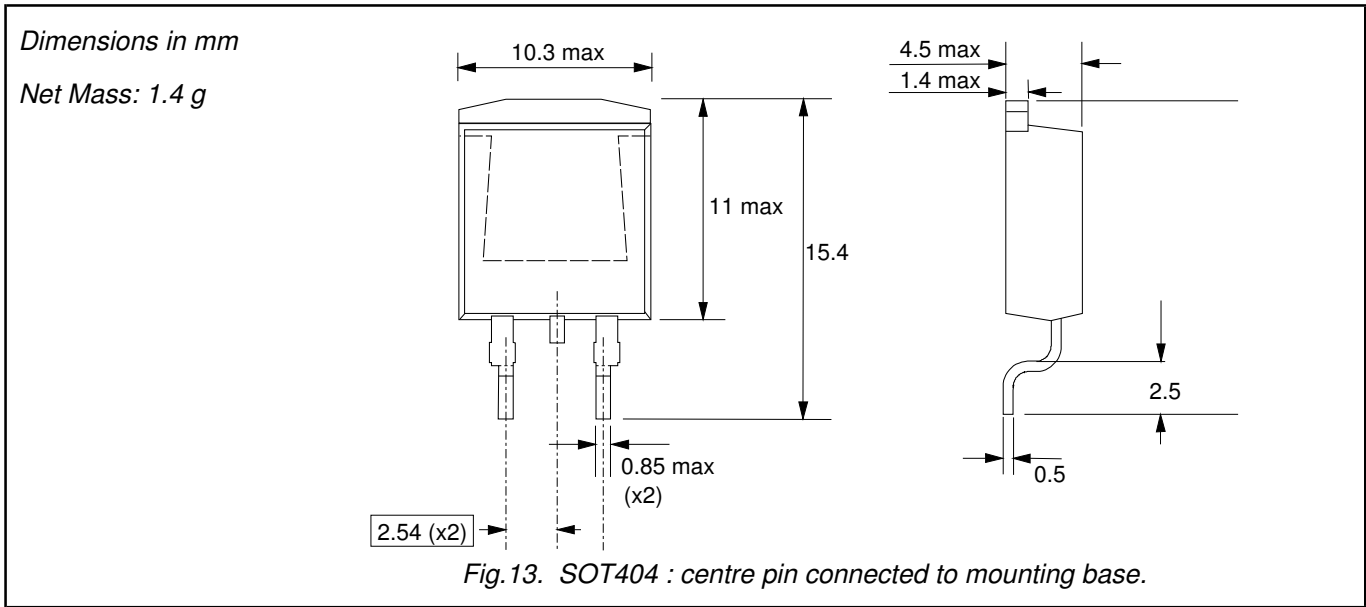
Notes

1. Refer to mounting instructions for SOT78 (TO220) envelopes.
2. Epoxy meets UL94 V0 at 1/8".

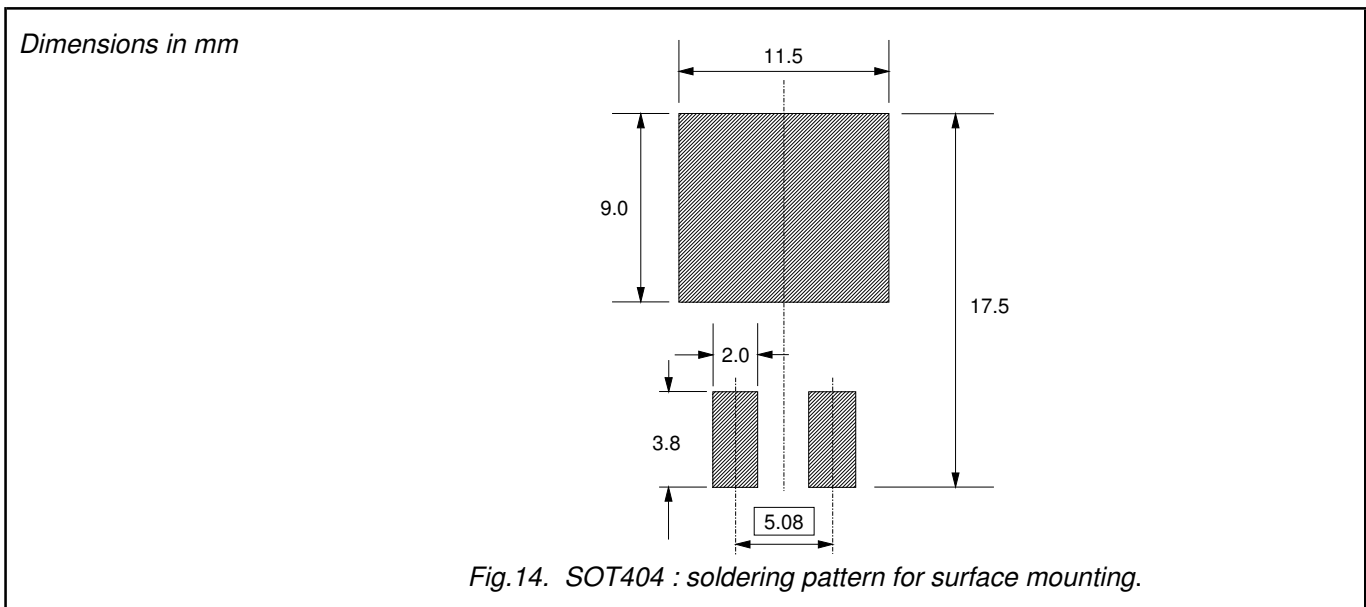
Rectifier diodes
ultrafast, rugged

BYV42E, BYV42EB series

MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

- 1. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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